



**THE DATASHEET OF
CIG22L6R8MNE**



Multilayer Power Inductor

CIG22L Series (2520/ EIA 1008)



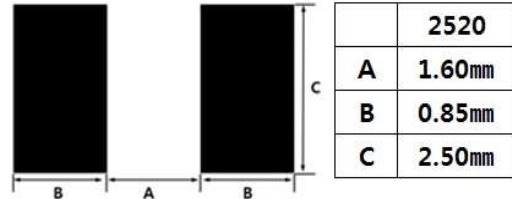
APPLICATION

Mobile phones, DSC, DVC, PDA etc. for DC-DC Converter

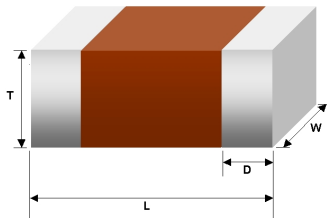
FEATURES

- Low DC resistance
- Magnetically shielded structure
- Free of all RoHS-regulated substances
- Monolithic structure for high reliability

RECOMMENDED LAND PATTERN



DIMENSION



| TYPE | Dimension [mm] | | | |
|------|----------------|---------|---------|-----------|
| | L | W | T | D |
| 22 | 2.5±0.2 | 2.0±0.2 | 0.9±0.1 | 0.55±0.25 |

DESCRIPTION

| Part no. | Size (inch/mm) | Inductance (uH)@1MHz | DC Resistance(Ω) | Rated Current (A) Max. |
|--------------|----------------|----------------------|------------------|------------------------|
| CIG22LR47MNE | 1008/2520 | 0.47 ±20 % | 0.040 ±25 % | 1.80 |
| CIG22L1R0MNE | 1008/2520 | 1.0 ±20 % | 0.060 ±25 % | 1.60 |
| CIG22L1R2MNE | 1008/2520 | 1.2 ±20 % | 0.065 ±25 % | 1.50 |
| CIG22L1R5MNE | 1008/2520 | 1.5 ±20 % | 0.070 ±25 % | 1.50 |
| CIG22L2R2MNE | 1008/2520 | 2.2 ±20 % | 0.080 ±25 % | 1.30 |
| CIG22L3R3MNE | 1008/2520 | 3.3 ±20 % | 0.100 ±25 % | 1.20 |
| CIG22L4R7MNE | 1008/2520 | 4.7 ±20 % | 0.110 ±25 % | 1.10 |
| CIG22L6R8MNE | 1008/2520 | 6.8 ±20 % | 0.203 ±30 % | 0.80 |
| CIG22L100MNE | 1008/2520 | 10.0 ±20 % | 0.323 ±30 % | 0.60 |

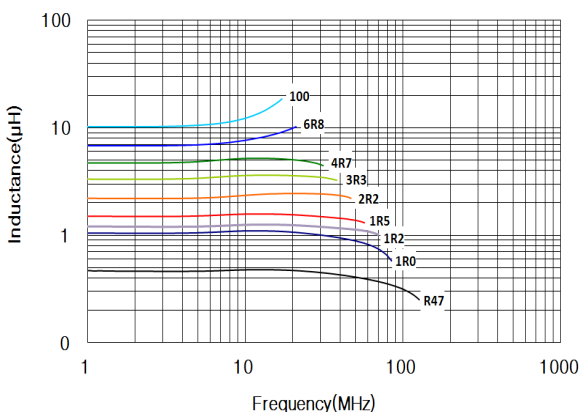
※ Rated Current (A): DC current value when the self-generation of heat rises to 40℃ (Reference ambient temperature:25℃)

※ Operating temperature range: -40 to +125℃ (Including self-temperature rise)

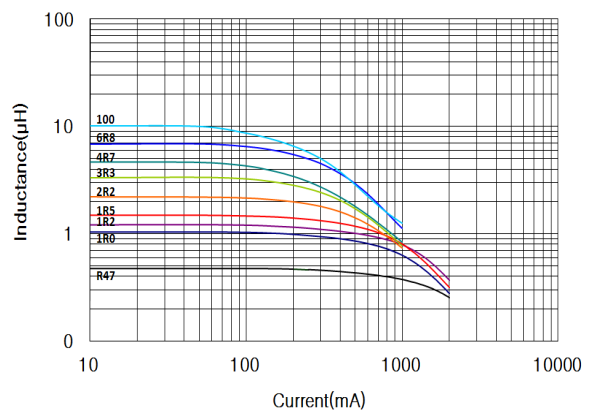
※ Test equipment: Agilent :E4991A+16092A

CHARACTERISTIC DATA

1) Frequency characteristics (Typ.)



2) DC Bias characteristics (Typ.)



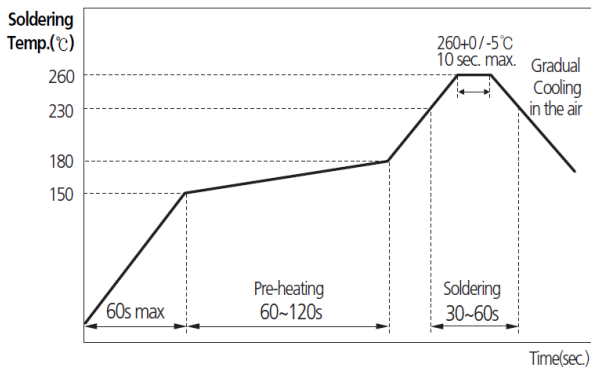
PRODUCT IDENTIFICATION

CI G 22 L 1R0 M N E
(1) (2) (3) (4) (5) (6) (7) (8)

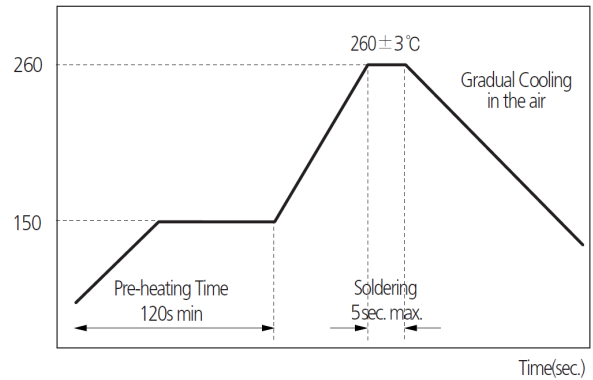
- (1) Chip Inductor
- (2) Power Inductor
- (3) Dimension
- (4) Product Series (L: Low Rdc)
- (5) Inductance (1R0:1.0uH)
- (6) Tolerance (M:±20%)
- (7) Thickness option(N:Standard, A:Thinner than standard, B:Thicker than standard)
- (8) Packaging(C:paper tape, E:embossed tape)

RECOMMENDED SOLDERING CONDITION

REFLOW SOLDERING



FLOW SOLDERING



PACKAGING

| Packaging Style | Quantity(pcs/reel) |
|-----------------|--------------------|
| Embossed Taping | 3,000 |

Any data in this sheet are subject to change, modify or discontinue without notice. The data sheets include the typical data for design reference only. If there is any question regarding the data sheets, please contact our sales personnel or application engineers.

Looking for pricing, stock, or lifecycle information?

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- ✓ Shortage Management
- ✓ Alternative Solution
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